## SUP10250E



**Vishay Siliconix** 

## N-Channel 250 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) MAX.	I <sub>D</sub> (A)	Q <sub>g</sub> (TYP.)		
250	0.0315 at V <sub>GS</sub> = 10 V	63	57.6 nC		
	0.0325 at V <sub>GS</sub> = 7.5 V	62	57.0110		



#### **Ordering Information:**

SUP10250E-GE3 (lead (Pb)-free and halogen-free)

### FEATURES

- ThunderFET<sup>®</sup> power MOSFET
- Tuned for the lowest R<sub>DS</sub>-C<sub>oss</sub> FOM
- Maximum 175 °C junction temperature
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### **APPLICATIONS**

- Power supplies:
  - Uninterruptible power supplies
  - AC/DC switch-mode power supplies
  - Lighting
- Synchronous rectification
- DC/DC converter
- Motor drive switch
- DC/AC inverter
- Solar micro inverter
- Class D audio amplifier



- COMPLIANT HALOGEN
- es G G S N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b>	$(T_C = 25 \ ^{\circ}C, \text{ unless other})$	rwise noted)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	250	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
Continuous Drain Current ( $T_{.1} = 150 ^{\circ}$ C)	T <sub>C</sub> = 25 °C		63		
Continuous Drain Current $(1_j = 150^{\circ} C)$	T <sub>C</sub> = 70 °C	I <sub>D</sub>	36.3	•	
Pulsed Drain Current (t = 100 μs)		I <sub>DM</sub>	150	A	
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	60		
Single Avalanche Energy <sup>a</sup>		E <sub>AS</sub>	180	mJ	
Movimum Dower Dissinction a	$T_{\rm C} = 25 ^{\circ}{\rm C} \qquad P_{\rm D} \qquad 375 ^{\rm b}$	w			
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 125 °C	PD	125 <sup>b</sup>	vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-Ambient (PCB mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.4	C/W	

Notes

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR4 material).

MAX.

MIN.

TYP.

**SUP10250E** 

UNIT

V nA μA MA A Ω S

pF

nC

Ω

ns

A V ns A µC

Static						_
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	250	-	-	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2	-	4	1
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 250	
		$V_{DS} = 250 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 250 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	-	150	
		$V_{DS}$ = 250 V, $V_{GS}$ = 0 V, $T_{J}$ = 175 °C	-	-	5	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10$ V, $V_{GS} = 10$ V	90	-	-	
Drain-Source On-State Resistance <sup>a</sup>	Б	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	-	0.0250	0.0315	
Drain-Source On-State Resistance ~	R <sub>DS(on)</sub>	$V_{GS} = 7.5 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	-	0.0260	0.0325	
Forward Transconductance <sup>a</sup>	<b>g</b> <sub>fs</sub>	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	-	63	-	
Dynamic <sup>b</sup>						
Input Capacitance	Ciss		-	3002	-	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 125 V, f = 1 MHz	-	184	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	18	-	
Total Gate Charge <sup>c</sup>	Qg		-	57.6	88	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 125 V, $V_{GS}$ = 10 V, $I_{D}$ = 60 A	-	15.1	-	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>		-	18.4	-	
Gate Resistance	Rg	f = 1 MHz	1.5	3.1	5	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	13	26	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 125 V, $R_L$ = 2.08 $\Omega$	-	93	186	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 60 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 1 $\Omega$	-	30	60	
Fall Time <sup>c</sup>	t <sub>f</sub>		-	72	144	
Drain-Source Body Diode Ratings an	d Characteri	stics <sup>b</sup> (T <sub>C</sub> = 25 °C)				
Pulsed Current (t = 100 µs)	I <sub>SM</sub>		-	-	100	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V	-	0.79	1.2	
Reverse Recovery Time	t <sub>rr</sub>		-	212	420	
Peak Reverse Recovery Charge	I <sub>RM(REC)</sub>	I <sub>F</sub> = 30 A, di/dt = 100 A/μs	-	14.5	29	1
Reverse Recovery Charge	Q <sub>rr</sub>		-	1.6	3.2	İ -

**TEST CONDITIONS** 

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

www.vishay.com

PARAMETER

**SPECIFICATIONS** (T<sub>J</sub> = 25 °C, unless otherwise noted)

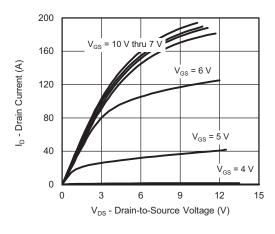
SYMBOL

c. Independent of operating temperature.

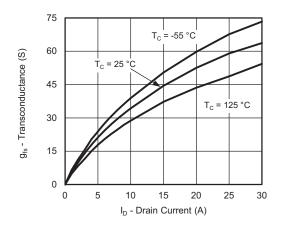
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



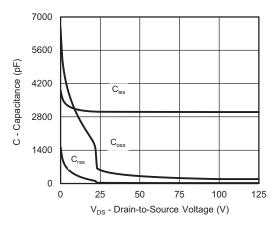
### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



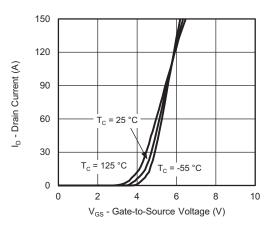
**Output Characteristics** 



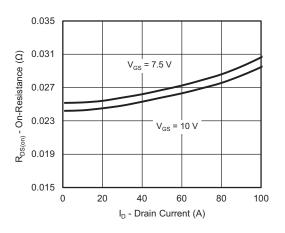
Transconductance



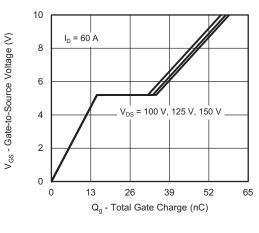
#### Capacitance







**On-Resistance vs. Drain Current** 



Gate Charge

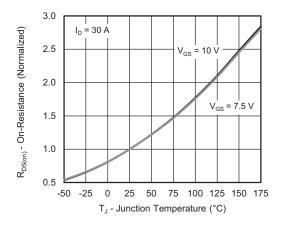
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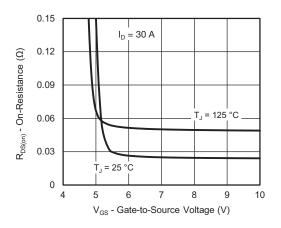
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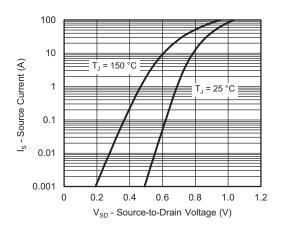
## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



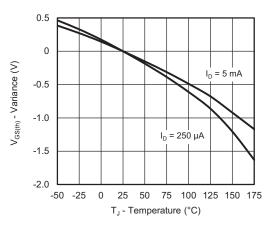
**On-Resistance vs. Junction Temperature** 



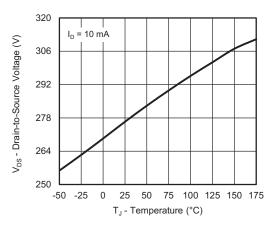
On-Resistance vs. Gate-to-Source Voltage



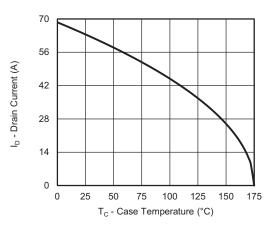
Source Drain Diode Forward Voltage



Threshold Voltage



Drain Source Breakdown vs. Junction Temperature



**Current Derating** 

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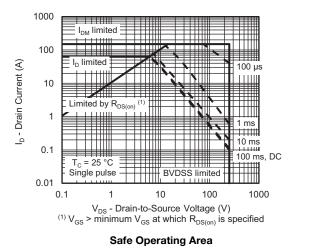
4

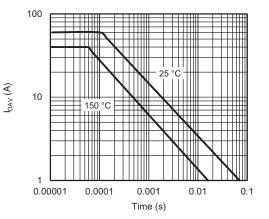
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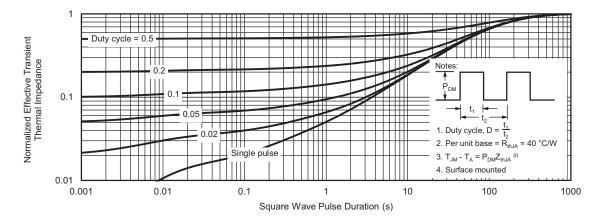


## **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time

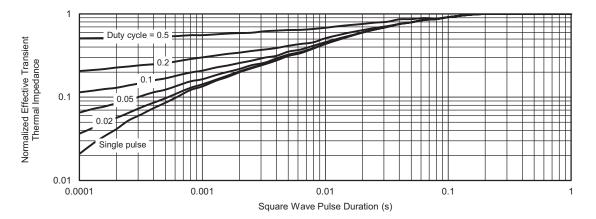


Normalized Thermal Transient Impedance, Junction-to-Ambient



Document Number: 79033

### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

The characteristics shown in the two graphs

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- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?79033.



## **TO-220AB**



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
	0413-Rev. P,		0.102	0.118

Note

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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